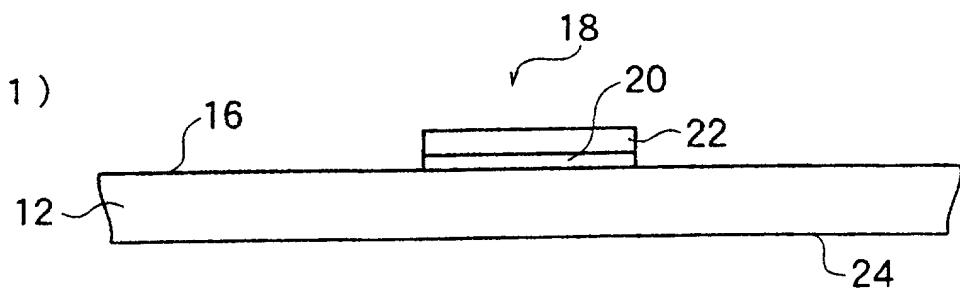
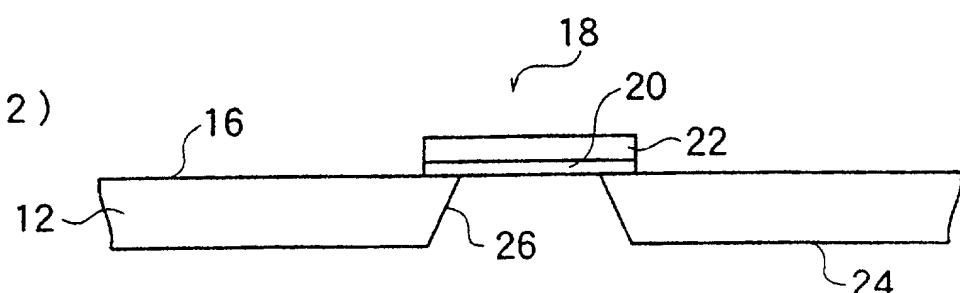


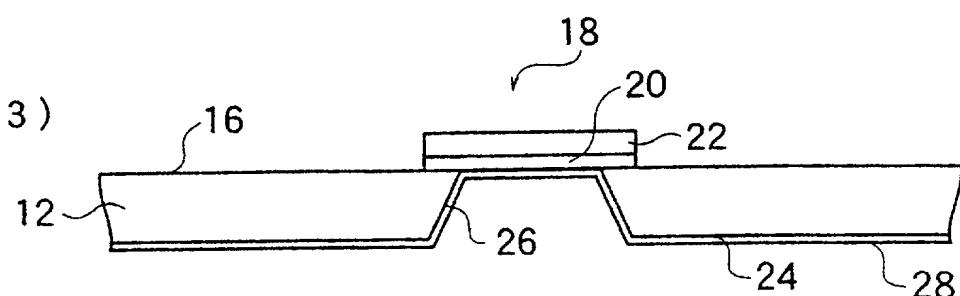
**Fig. 1 (1)**



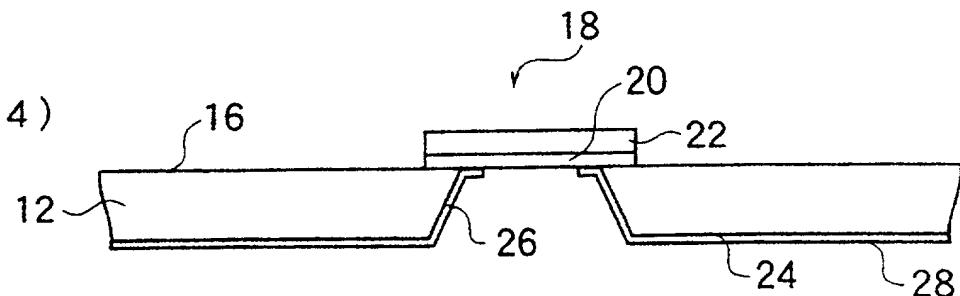
**Fig. 1 (2)**



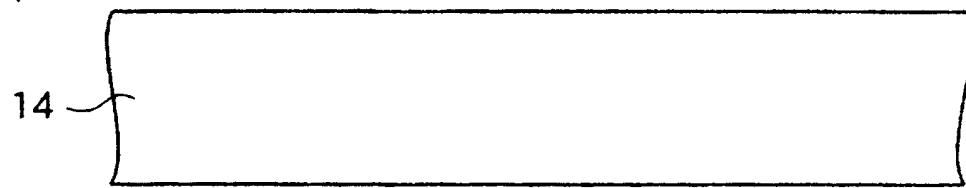
**Fig. 1 (3)**



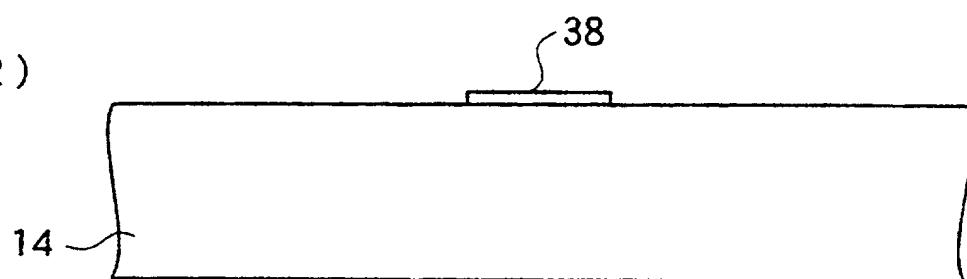
**Fig. 1 (4)**



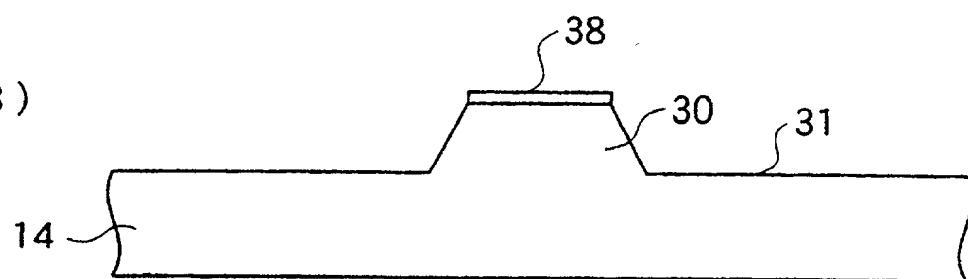
**Fig. 2 (1)**



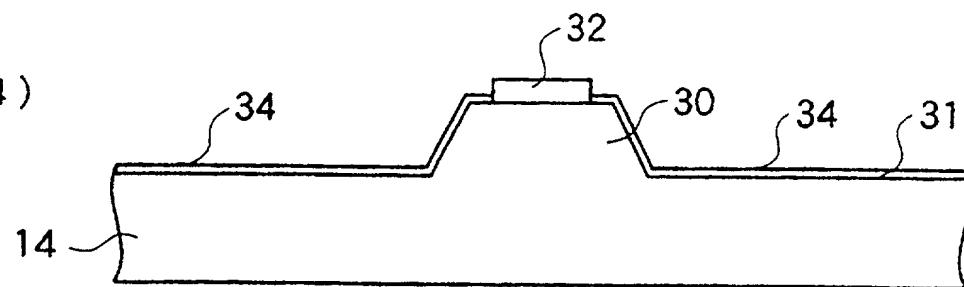
**Fig. 2(2)**



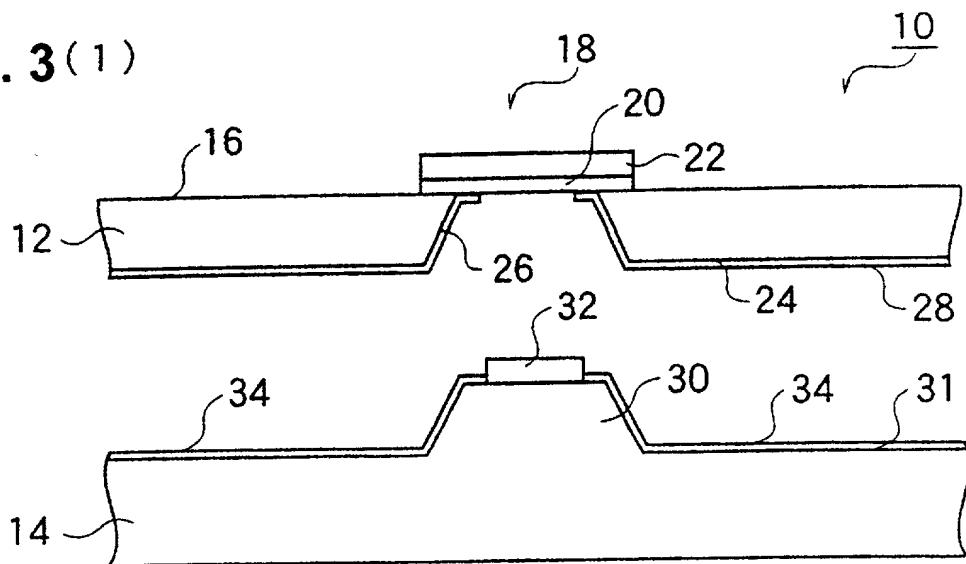
**Fig. 2 (3)**



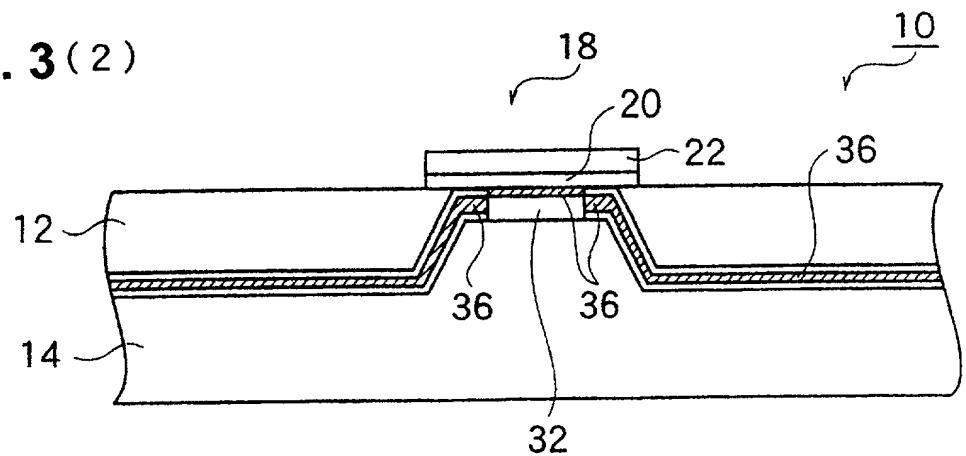
**Fig. 2(4)**



**Fig. 3(1)**



**Fig. 3(2)**



10 : Semiconductor device

16 : Surface

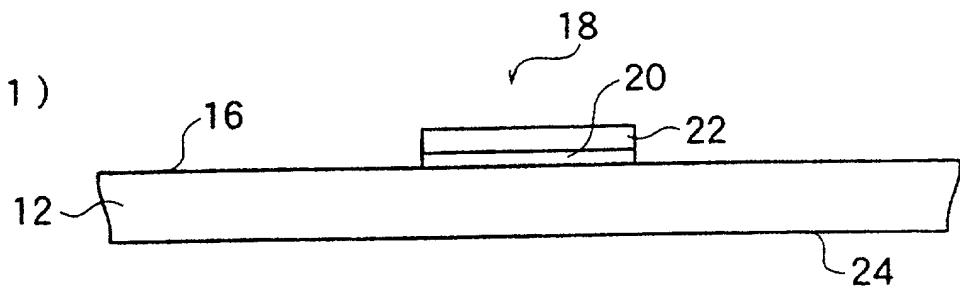
12 : First semiconductor chip

18 : Electrode

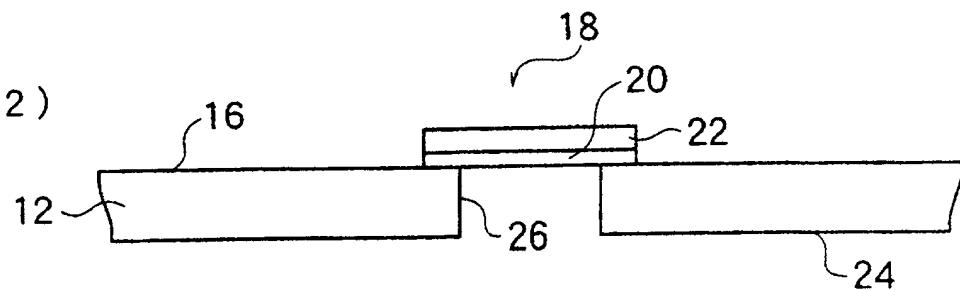
14 : Second semiconductor chip

32 : Abutting electrode

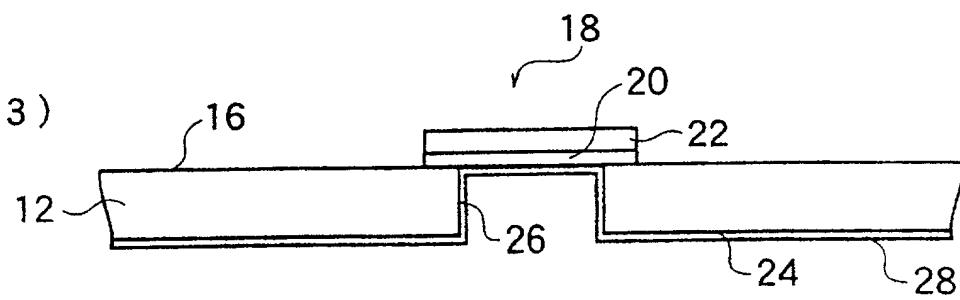
**Fig. 4 (1)**



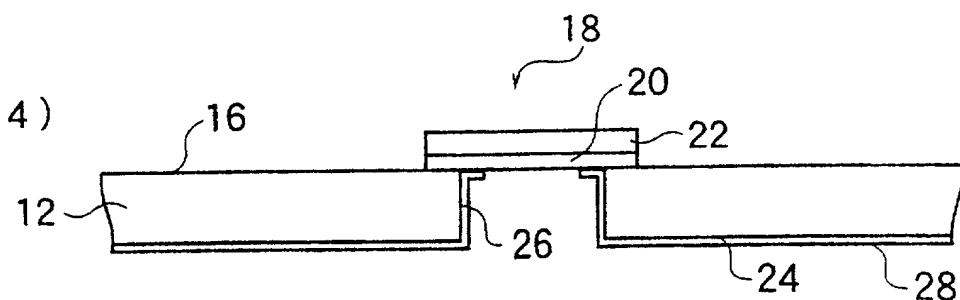
**Fig. 4 (2)**



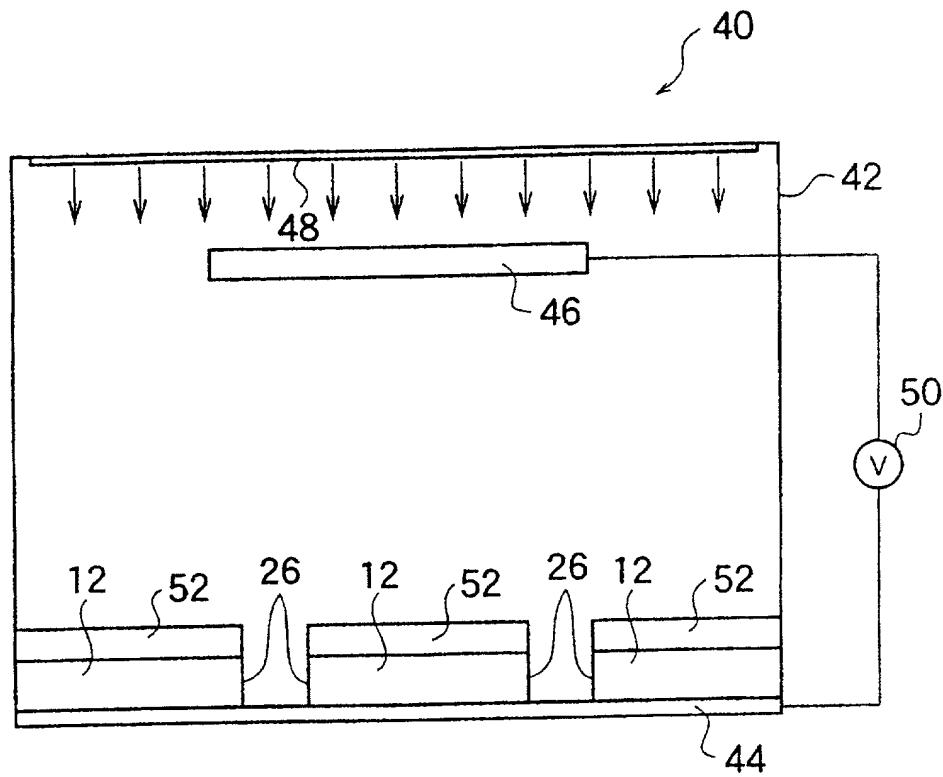
**Fig. 4 (3)**



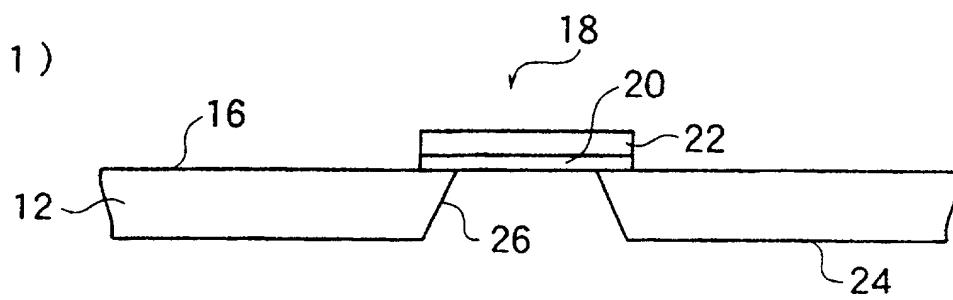
**Fig. 4 (4)**



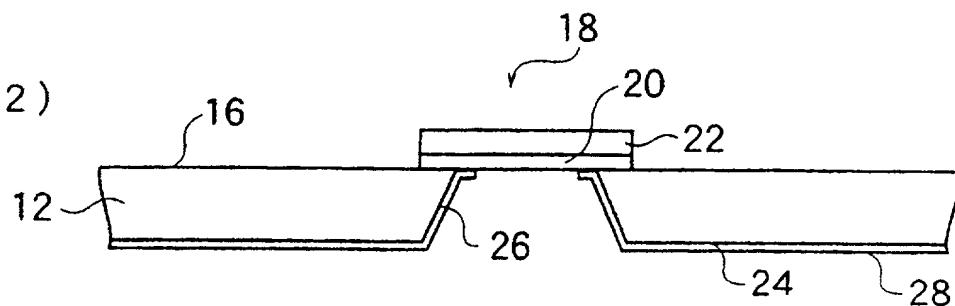
**Fig. 5**



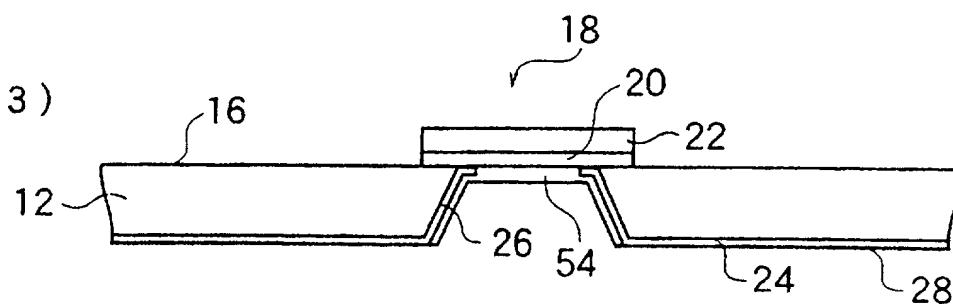
**Fig. 6 (1)**



**Fig. 6 (2)**



**Fig. 6 (3)**



**Fig. 6 (4)**

